

1. General description

Silicon Carbide Schottky diode in a TO252 (DPAK) plastic package, designed for high frequency switched-mode power supplies.

2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

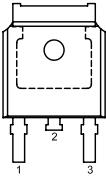
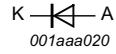
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{RRM}	repetitive peak reverse voltage		650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 125$ °C; Fig. 1 ; Fig. 2 ; Fig. 3	6			A
T_j	junction temperature		175			°C
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 6$ A; $T_j = 25$ °C; Fig. 5	-	1.5	1.7	V
		$I_F = 6$ A; $T_j = 150$ °C; Fig. 5	-	1.8	2.1	V
Dynamic characteristics						
Q_r	recovered charge	$I_F = 6$ A; $dI_F/dt = 500$ A/μs; $V_R = 400$ V; $T_j = 25$ °C; Fig. 7	-	9	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		
2	K	cathode [1]		
3	A	anode		
mb	K	mounting base; connected to cathode		

[1] It is not possible to connect to pin 2 of the TO252 package.

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
GKTSC06650D	TO252	GKTSC06650D6J	Reel	2500	TO252NS	04-Nov-2015

7. Marking

Table 4. Marking codes

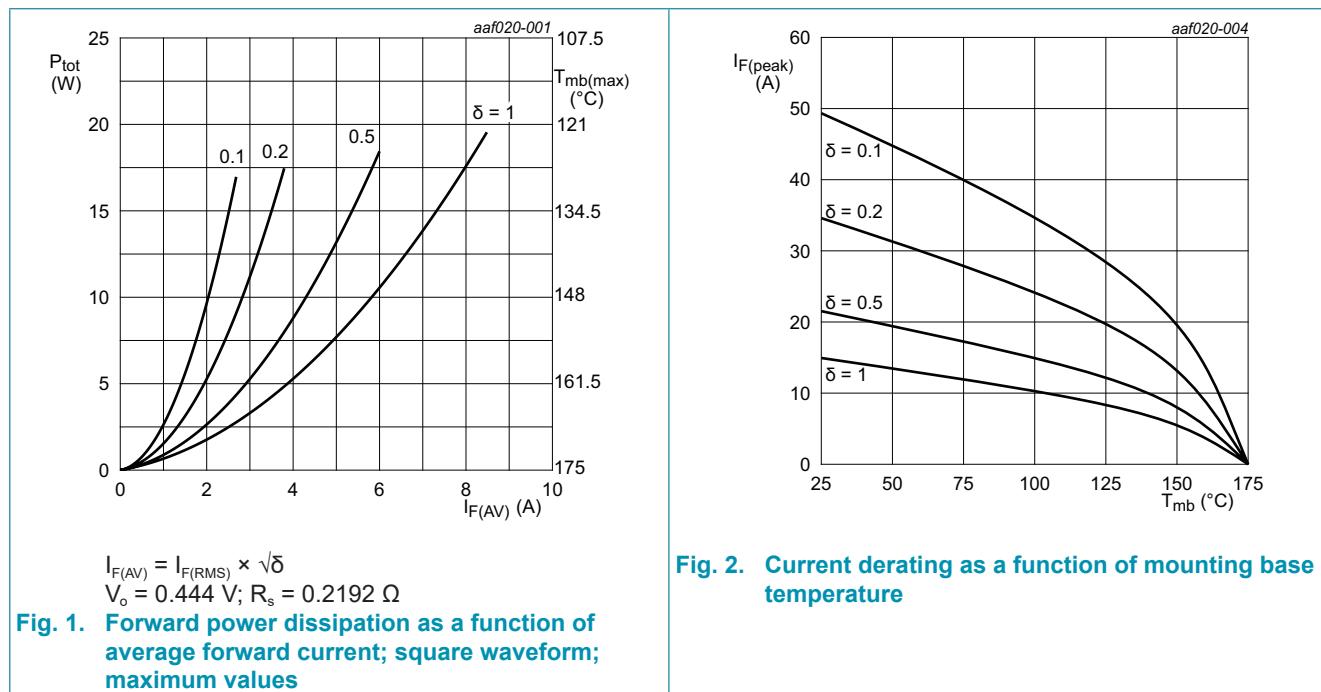
Type number	Marking codes
GKTSC06650D	GKTSC 06650D

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		650	V
V_{RWM}	crest working reverse voltage		650	V
V_R	reverse voltage	DC	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 125^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	6	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\ \mu\text{s}$; $T_{mb} \leq 125^\circ\text{C}$; square-wave pulse	12	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\ \text{ms}$; $T_{j(\text{init})} = 25^\circ\text{C}$; sine-wave pulse	36	A
		$t_p = 10\ \mu\text{s}$; $T_{j(\text{init})} = 25^\circ\text{C}$; square-wave pulse	310	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 10\ \text{ms}$	6.48	A^2s
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



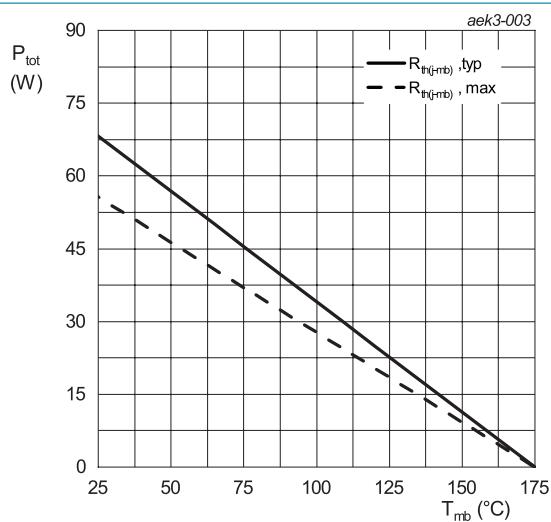


Fig. 3. Total power dissipation as a function of mounting base temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	with heatsink compound; Fig. 4		-	2.2	2.7	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

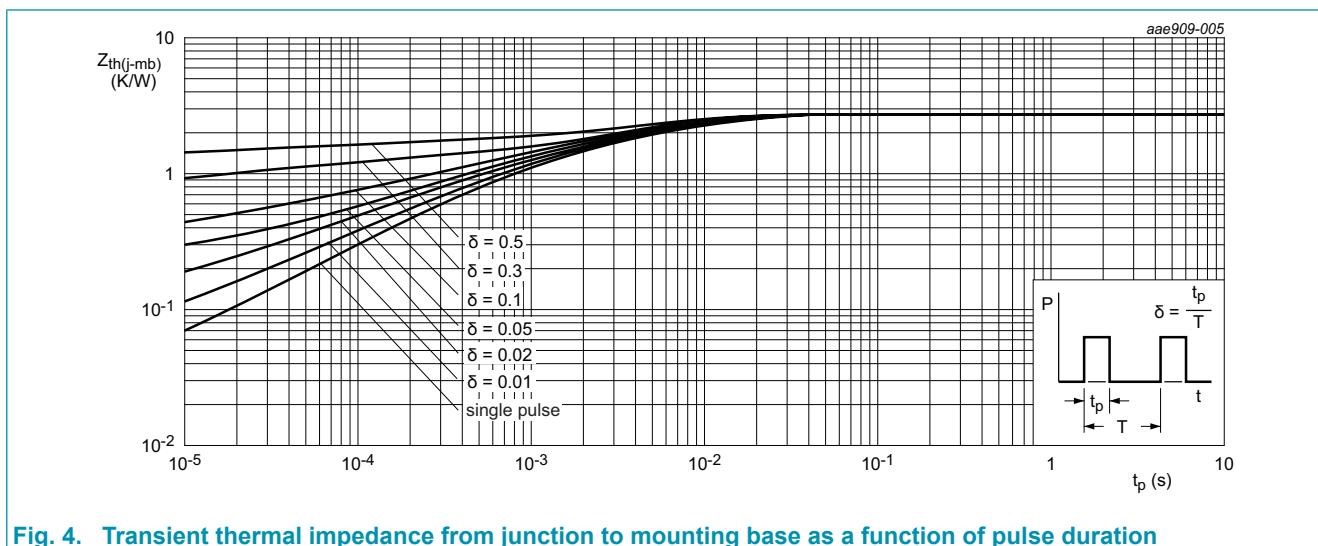
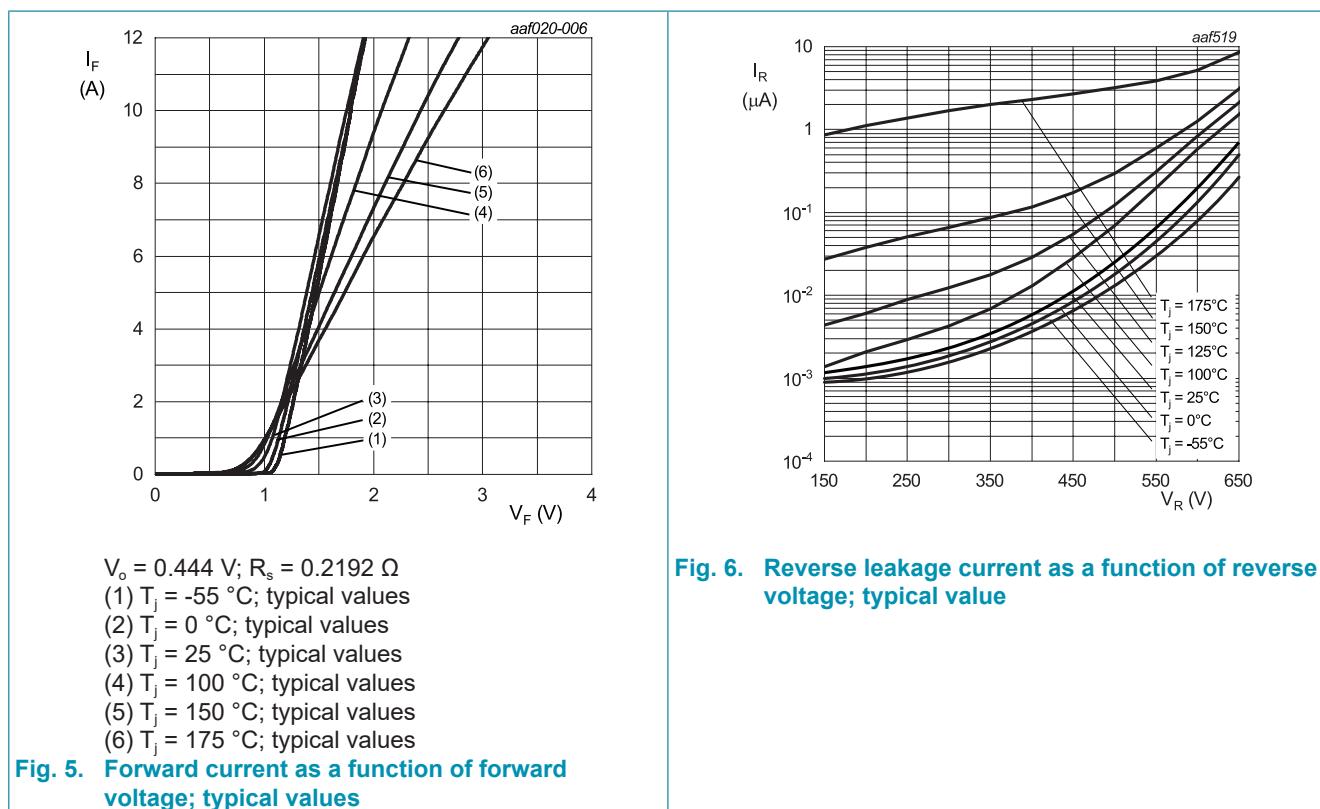


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 6 A; T _j = 25 °C; Fig. 5		-	1.5	1.7	V
		I _F = 6 A; T _j = 150 °C; Fig. 5		-	1.8	2.1	V
I _R	reverse current	V _R = 650 V; T _j = 25 °C; Fig. 6		-	-	40	μA
		V _R = 650 V; T _j = 150 °C; Fig. 6		-	-	160	μA
Dynamic characteristics							
Q _r	recovered charge	I _F = 6 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _j = 25 °C; Fig. 7		-	9	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C		-	190	-	pF
		f = 1 MHz; V _R = 300 V; T _j = 25 °C		-	30	-	pF
		f = 1 MHz; V _R = 600 V; T _j = 25 °C		-	29	-	pF
E _{as}	non-repetitive avalanche energy	I _R = 4.25 A; L = 5 mH; T _{j(init)} = 25 °C		45	-	-	mJ



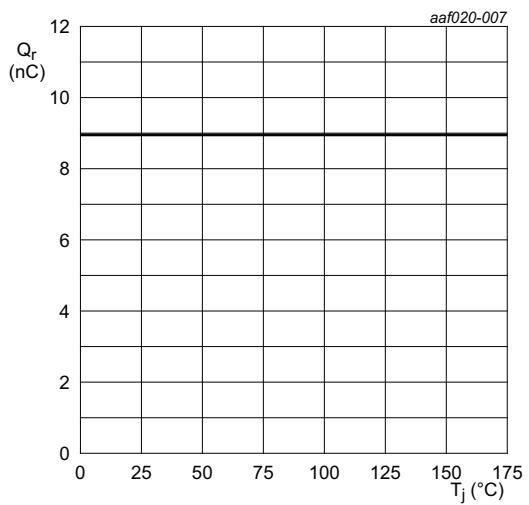
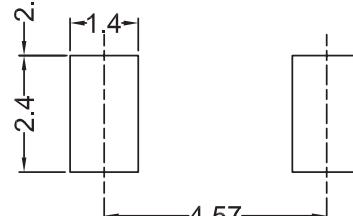
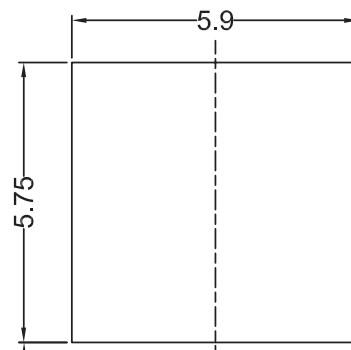
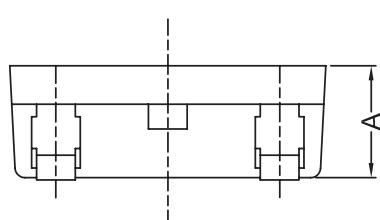
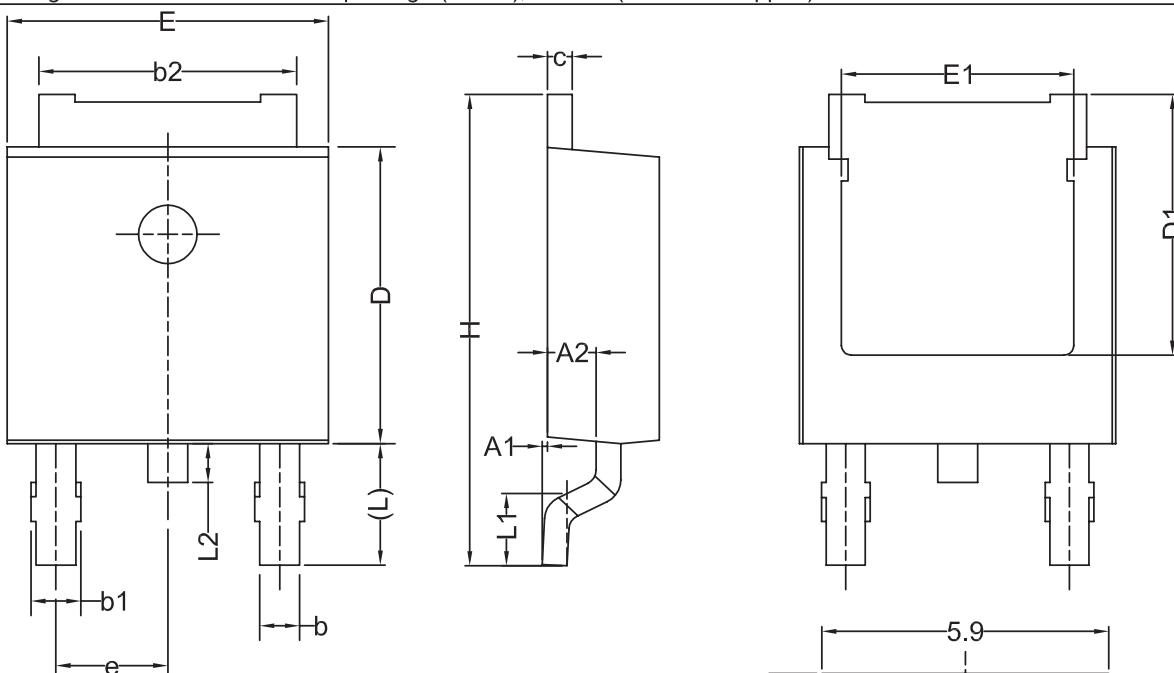


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

TO252



Recommended Footprint

	A	A1	A2	b	b1	b2	c	D	D1	e	E	E1	H	L	L1	L2
min	2.20	0	0.90	0.71	0.72	5.23	0.47	5.98	5.25	2.285 (typ.)	6.47	4.70	9.60	2.90 (Ref.)	1.40	0.50
max	2.38	0.10	1.10	0.89	1.10	5.43	0.60	6.22	---	6.73	---	10.40	1.70	1.00		

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